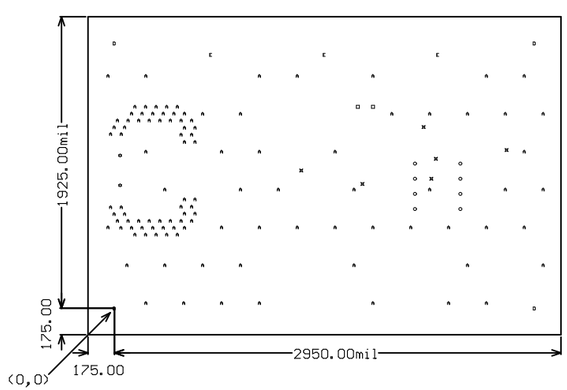
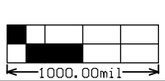
STACKUP TABLE:

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	2.80mil		
4	Dielectric1	FR-4	59.20mil	4.8	
5	Bottom Layer	Copper	2.80mil		
6	Bottom Solder	Solder Resist	0.40mil	3.5	
7	Bottom Overlay				

DRILL TABLE:

Symbol	Count	Hole Size	Plated	Hole Type	Tolerance(Mils)	Tenting
A	109	12.00mil (0.305mm)	PTH	Round	+0/-12	Both
O	8	35.43mil (0.900mm)	PTH	Round		
⌘	6	20.00mil (0.508mm)	PTH	Round		
D	4	125.98mil (3.200mm)	PTH	Round	+/-3	
E	3	214.57mil (5.450mm)	PTH	Round	+/-3	
□	2	40.00mil (1.016mm)	PTH	Round		
✡	2	51.18mil (1.300mm)	PTH	Round		
	134 Total					





FAB NOTES:

1. THE SOLDER MASK IMAGES THAT ARE THE SAME SIZE AS THE COMPONENT PADS MAY BE ENLARGED AS PER THE MANUFACTURING CAPABILITIES BUT NOT BEYOND 0.08MM PER SIDE OR 0.15MM OVERALL.
   ALL OTHER SOLDER MASK IMAGES SHALL NOT BE MODIFIED.

DESIGN INFORMATION

MIN. TRACK WIDTH: 20 MIL
MIN. CLEARANCE: 19.7 MIL
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
☐ FR-408 ☒ FR-4 High Tg ☐ OTHER _____
THICKNESS: ☐ 62 MIL (1.6mm) +/-10% ☒ OTHER 2oz copper
TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- _____
BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- _____

DRILLING:
REFERENCE: ☒ AS SHOWN ☒ NC_DRILL FILES
PTH COPPER THICKNESS: ☒ 20-30 um ☐ OTHER _____

BOARD FINISH:
SILKSCREEN: ☒ TOP ☐ BOTTOM
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER _____
SOLDER RESIST COLOR: ☒ GREEN ☐ OTHER _____
☒ MATTE ☐ SEMI-GLOSS

SURFACE FINISH: ☒ IMMERSION GOLD (ENIG) ☐ ENEPIG
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER _____

ARRAY/PANEL: ☐ CUT AND TRIM PER M1 BOARD OUTLINE
☐ N.C. ROUTE ☒ V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3
☒ RoHS ☐ OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: ☐ YES
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER
☐ XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
☐ XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
☐ OUTER XX MIL VIAS REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
☐ LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE

TEXAS INSTRUMENTS

PROJECT TITLE: INA901EVM-CVAL
DESIGNED FOR: Public Release
FILE NAME: SLHR017B_PCB.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SLHR017	REV: B	SVN REV: Not In VersionControl
LAYER NAME = [redacted]ions	TID #: N/A		
PLOT NAME = Fabrication Drawing	GENERATED : 5/22/2020 12:20:26 PM		TEXAS INSTRUMENTS

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ENGINEER: Carolus Andrews
LAYOUT BY: Carolus Andrews
SCALE: 1.00
ALTIUM DESIGNER VERSION: 18.1.9.240

WO#307451-7449-D